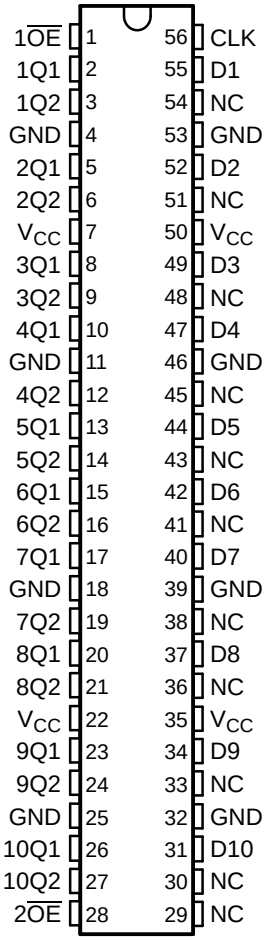
# SN74ALVCH16820
# 3.3-V 10-BIT FLIP-FLOP WITH DUAL OUTPUTS AND 3-STATE OUTPUTS

SCES035G – JULY 1995 – REVISED OCTOBER 2004

## FEATURES

- **Member of the Texas Instruments Widebus™ Family**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Latch-Up Performance Exceeds 250 mA Per JESD 17**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**

**DGG OR DL PACKAGE**
**(TOP VIEW)**




NC − No internal connection

## DESCRIPTION/ORDERING INFORMATION

This 10-bit flip-flop is designed for 1.65-V to 3.6-V $V_{CC}$ operation.

The flip-flops of the SN74ALVCH16820 are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the device provides true data at the Q outputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the ten outputs in either a normal logic state (high or low logic level) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$ input does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to $V_{CC}$ through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

**ORDERING INFORMATION**

| $T_A$ | PACKAGE(1) | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|---|---|---|---|---|
| -40°C to 85°C | SSOP - DL | Tube | SN74ALVCH16820DL | ALVCH16820 |
| | | Tape and reel | SN74ALVCH16820DLR | |
| | TSSOP - DGG | Tape and reel | SN74ALVCH16820DGGR | ALVCH16820 |

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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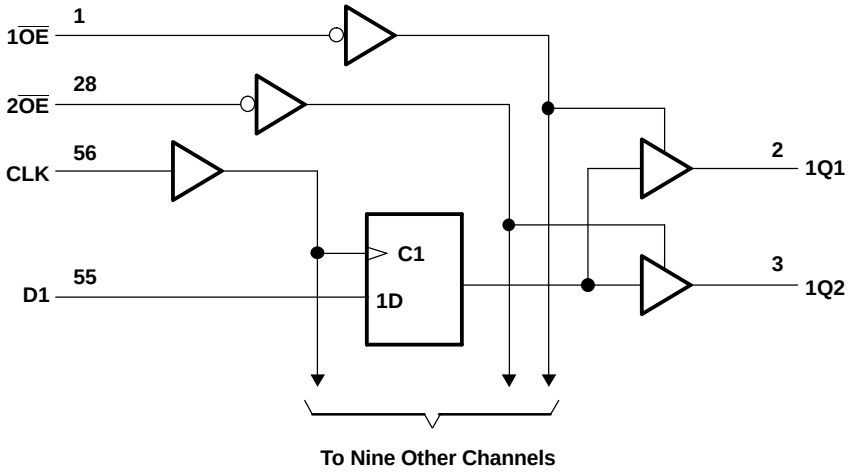
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### FUNCTION TABLE
### (each flip-flop)

| INPUTS | | | OUTPUT |
|---|---|---|---|
| $n\overline{OE}$ (1) | CLK | D | Qn (1) |
| L | ↑ | H | H |
| L | ↑ | L | L |
| L | L | X | $Q_0$ |
| H | X | X | Z |

(1) n = 1, 2

### LOGIC DIAGRAM (POSITIVE LOGIC)



## ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

| | | | MIN | MAX | UNIT |
|---|---|---|---|---|---|
| $V_{CC}$ | Supply voltage range | | -0.5 | 4.6 | V |
| $V_I$ | Input voltage range(2) | | -0.5 | 4.6 | V |
| $V_O$ | Output voltage range(2)(3) | | -0.5 | $V_{CC}$ + 0.5 | V |
| $I_{IK}$ | Input clamp current | $V_I$ < 0 | | -50 | mA |
| $I_{OK}$ | Output clamp current | $V_O$ < 0 | | -50 | mA |
| $I_O$ | Continuous output current | | | ±50 | mA |
| | Continuous current through each $V_{CC}$ or GND | | | ±100 | mA |
| $\theta_{JA}$ | Package thermal impedance(4) | DGG package | | 64 | °C/W |
| | | DL package | | 56 | |
| $T_{stg}$ | Storage temperature range | | -65 | 150 | °C |

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
(3) This value is limited to 4.6 V maximum.
(4) The package thermal impedance is calculated in accordance with JESD 51-7.

## RECOMMENDED OPERATING CONDITIONS(1)

| | | | MIN | MAX | UNIT |
|---|---|---|---|---|---|
| $V_{CC}$ | Supply voltage | | 1.65 | 3.6 | V |
| $V_{IH}$ | High-level input voltage | $V_{CC}$ = 1.65 V to 1.95 V | 0.65 × $V_{CC}$ | | V |
| | | $V_{CC}$ = 2.3 V to 2.7 V | 1.7 | | |
| | | $V_{CC}$ = 2.7 V to 3.6 V | 2 | | |
| $V_{IL}$ | Low-level input voltage | $V_{CC}$ = 1.65 V to 1.95 V | | 0.35 × $V_{CC}$ | V |
| | | $V_{CC}$ = 2.3 V to 2.7 V | | 0.7 | |
| | | $V_{CC}$ = 2.7 V to 3.6 V | | 0.8 | |
| $V_I$ | Input voltage | | 0 | $V_{CC}$ | V |
| $V_O$ | Output voltage | | 0 | $V_{CC}$ | V |
| $I_{OH}$ | High-level output current | $V_{CC}$ = 1.65 V | | -4 | mA |
| | | $V_{CC}$ = 2.3 V | | -12 | |
| | | $V_{CC}$ = 2.7 V | | -12 | |
| | | $V_{CC}$ = 3 V | | -24 | |
| $I_{OL}$ | Low-level output current | $V_{CC}$ = 1.65 V | | 4 | mA |
| | | $V_{CC}$ = 2.3 V | | 12 | |
| | | $V_{CC}$ = 2.7 V | | 12 | |
| | | $V_{CC}$ = 3 V | | 24 | |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | | | 10 | ns/V |
| $T_A$ | Operating free-air temperature | | -40 | 85 | °C |

(1) All unused control inputs of the device must be held at $V_{CC}$ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | $V_{CC}$ | MIN | TYP(1) | MAX | UNIT |
|---|---|---|---|---|---|---|---|
| $V_{OH}$ | | $I_{OH}$ = -100 µA | 1.65 V to 3.6 V | $V_{CC}$ - 0.2 | | | V |
| | | $I_{OH}$ = -4 mA | 1.65 V | 1.2 | | | |
| | | $I_{OH}$ = -6 mA | 2.3 V | 2 | | | |
| | | $I_{OH}$ = -12 mA | 2.3 V | 1.7 | | | |
| | | | 2.7 V | 2.2 | | | |
| | | | 3 V | 2.4 | | | |
| | | $I_{OH}$ = -24 mA | 3 V | 2 | | | |
| $V_{OL}$ | | $I_{OL}$ = 100 µA | 1.65 V to 3.6 V | | | 0.2 | V |
| | | $I_{OL}$ = 4 mA | 1.65 V | | | 0.45 | |
| | | $I_{OL}$ = 6 mA | 2.3 V | | | 0.4 | |
| | | $I_{OL}$ = 12 mA | 2.3 V | | | 0.7 | |
| | | | 2.7 V | | | 0.4 | |
| | | $I_{OL}$ = 24 mA | 3 V | | | 0.55 | |
| $I_I$ | | $V_I$ = $V_{CC}$ or GND | 3.6 V | | | ±5 | µA |
| $I_{I(hold)}$ | | $V_I$ = 0.58 V | 1.65 V | 25 | | | µA |
| | | $V_I$ = 1.07 V | 1.65 V | -25 | | | |
| | | $V_I$ = 0.7 V | 2.3 V | 45 | | | |
| | | $V_I$ = 1.7 V | 2.3 V | -45 | | | |
| | | $V_I$ = 0.8 V | 3 V | 75 | | | |
| | | $V_I$ = 2 V | 3 V | -75 | | | |
| | | $V_I$ = 0 to 3.6 V(2) | 3.6 V | | | ±500 | |
| $I_{OZ}$ | | $V_O$ = $V_{CC}$ or GND | 3.6 V | | | ±10 | µA |
| $I_{CC}$ | | $V_I$ = $V_{CC}$ or GND, $I_O$ = 0 | 3.6 V | | | 40 | µA |
| $\Delta I_{CC}$ | | One input at $V_{CC}$ - 0.6 V, Other inputs at $V_{CC}$ or GND | 3 V to 3.6 V | | | 750 | µA |
| $C_i$ | Control inputs | $V_I$ = $V_{CC}$ or GND | 3.3 V | | 3.5 | | pF |
| | Data inputs | | | | 6 | | |
| $C_o$ | Outputs | $V_O$ = $V_{CC}$ or GND | 3.3 V | | 7 | | pF |

(1) All typical values are at $V_{CC}$ = 3.3 V, $T_A$ = 25°C.
(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

## TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

| | | $V_{CC}$ = 1.8 V | | $V_{CC}$ = 2.5 V ± 0.2 V | | $V_{CC}$ = 2.7 V | | $V_{CC}$ = 3.3 V ± 0.3 V | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|
| | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| $f_{clock}$ | Clock frequency | | (1) | | 150 | | 150 | | 150 | MHz |
| $t_w$ | Pulse duration, CLK high or low | (1) | | 3.3 | | 3.3 | | 3.3 | | ns |
| $t_{su}$ | Setup time, data before CLK↑ | (1) | | 1.7 | | 1.8 | | 1.4 | | ns |
| $t_h$ | Hold time, data after CLK↑ | (1) | | 1.1 | | 1.1 | | 1 | | ns |

(1) This information was not available at the time of publication.

## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC}$ = 1.8 V | | $V_{CC}$ = 2.5 V ± 0.2 V | | $V_{CC}$ = 2.7 V | | $V_{CC}$ = 3.3 V ± 0.3 V | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| $f_{max}$ | | | (1) | | 150 | | 150 | | 150 | | MHz |
| $t_{pd}$ | CLK | Q | | (1) | 1 | 5.9 | | 5.5 | 1 | 4.8 | ns |
| $t_{en}$ | $\overline{OE}$ | Q | | (1) | 1 | 6.4 | | 6.1 | 1 | 5 | ns |
| $t_{dis}$ | $\overline{OE}$ | Q | | (1) | 1 | 5.7 | | 5 | 1 | 4.5 | ns |

(1) This information was not available at the time of publication.

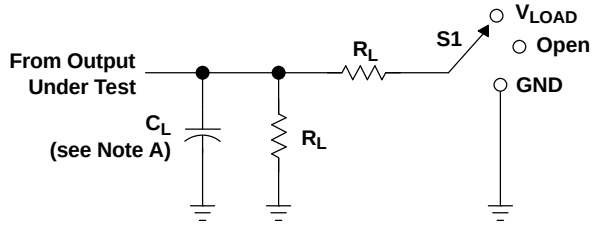
## OPERATING CHARACTERISTICS

$T_A$ = 25°C

| PARAMETER | | | TEST CONDITIONS | $V_{CC}$ = 1.8 V | $V_{CC}$ = 2.5 V | $V_{CC}$ = 3.3 V | UNIT |
|---|---|---|---|---|---|---|---|
| | | | | TYP | TYP | TYP | |
| $C_{pd}$ | Power dissipation capacitance | All outputs enabled | $C_L$ = 50 pF, f = 10 MHz | (1) | 60 | 63 | pF |
| | | All outputs disabled | | (1) | 38 | 46 | |

(1) This information was not available at the time of publication.

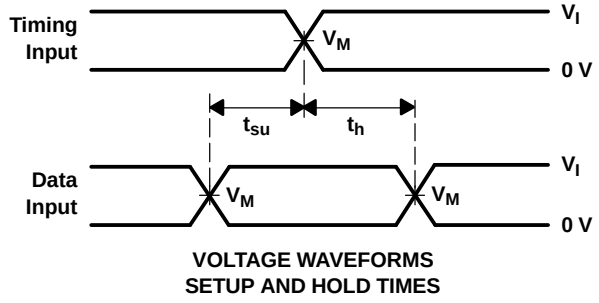
## PARAMETER MEASUREMENT INFORMATION



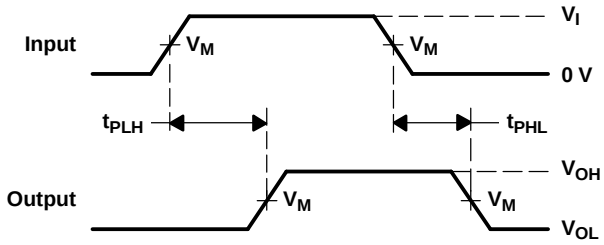

LOAD CIRCUIT

| TEST | S1 |
|---|---|
| $t_{pd}$<br>$t_{PLZ}/t_{PZL}$<br>$t_{PHZ}/t_{PZH}$ | Open<br>$V_{LOAD}$<br>GND |

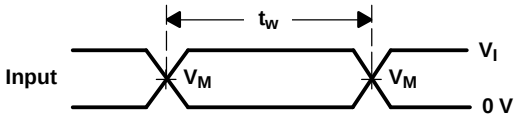
| $V_{CC}$ | INPUT | | $V_M$ | $V_{LOAD}$ | $C_L$ | $R_L$ | $V_\Delta$ |
|---|---|---|---|---|---|---|---|
| | $V_I$ | $t_r/t_f$ | | | | | |
| 1.8 V | $V_{CC}$ | ≤2 ns | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 1 kΩ | 0.15 V |
| 2.5 V ± 0.2 V | $V_{CC}$ | ≤2 ns | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 500 Ω | 0.15 V |
| 2.7 V | 2.7 V | ≤2.5 ns | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |
| 3.3 V ± 0.3 V | 2.7 V | ≤2.5 ns | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |



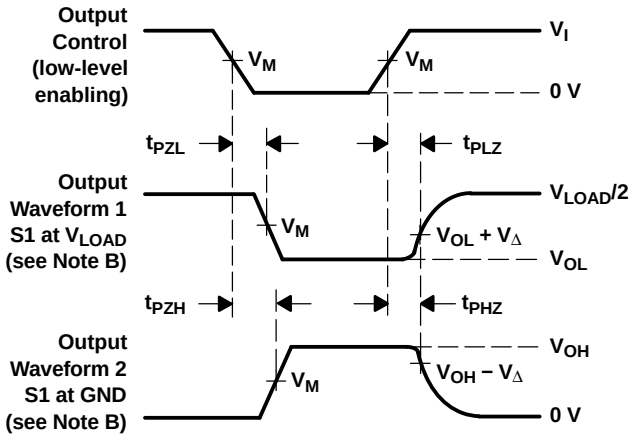

VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES




VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES




VOLTAGE WAVEFORMS
PULSE DURATION




VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. $C_L$ includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $Z_O$ = 50 Ω.
D. The outputs are measured one at a time, with one transition per measurement.
E. $t_{PLZ}$ and $t_{PHZ}$ are the same as $t_{dis}$.
F. $t_{PZL}$ and $t_{PZH}$ are the same as $t_{en}$.
G. $t_{PLH}$ and $t_{PHL}$ are the same as $t_{pd}$.
H. All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) |
|---|---|---|---|---|---|---|---|---|
| 74ALVCH16820DGGRE4 | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74ALVCH16820DGGRG4 | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74ALVCH16820DLRG4 | ACTIVE | SSOP | DL | 56 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74ALVCH16820DGGR | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74ALVCH16820DLR | ACTIVE | SSOP | DL | 56 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

(1) The marketing status values are defined as follows:
**ACTIVE:** Product device recommended for new designs.
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
**TBD:** The Pb-Free/Green conversion plan has not been defined.
**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

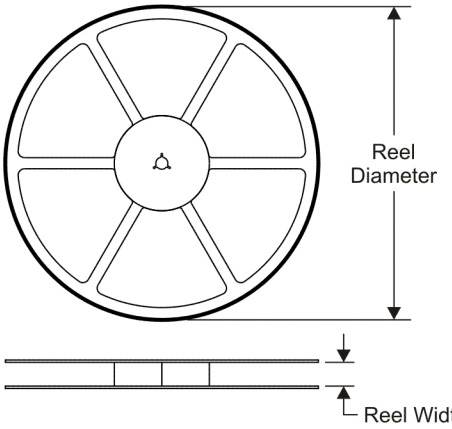
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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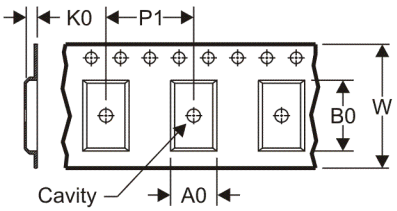
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## TAPE AND REEL INFORMATION

**REEL DIMENSIONS**

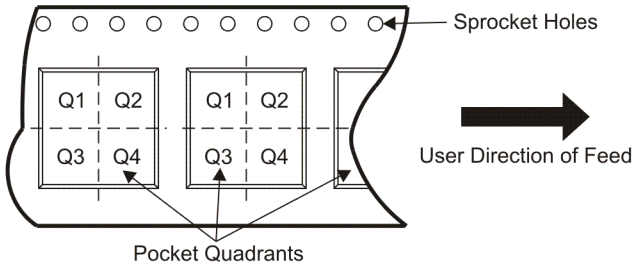



**TAPE DIMENSIONS**




| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

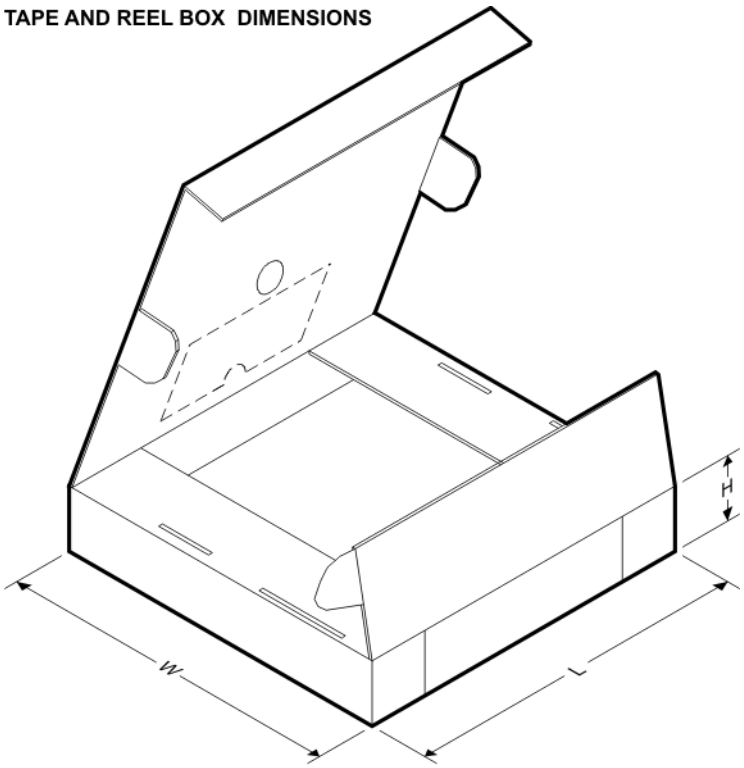
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| SN74ALVCH16820DGGR | TSSOP | DGG | 56 | 2000 | 330.0 | 24.4 | 8.6 | 15.6 | 1.8 | 12.0 | 24.0 | Q1 |
| SN74ALVCH16820DLR | SSOP | DL | 56 | 1000 | 330.0 | 32.4 | 11.35 | 18.67 | 3.1 | 16.0 | 32.0 | Q1 |

**TAPE AND REEL BOX DIMENSIONS**

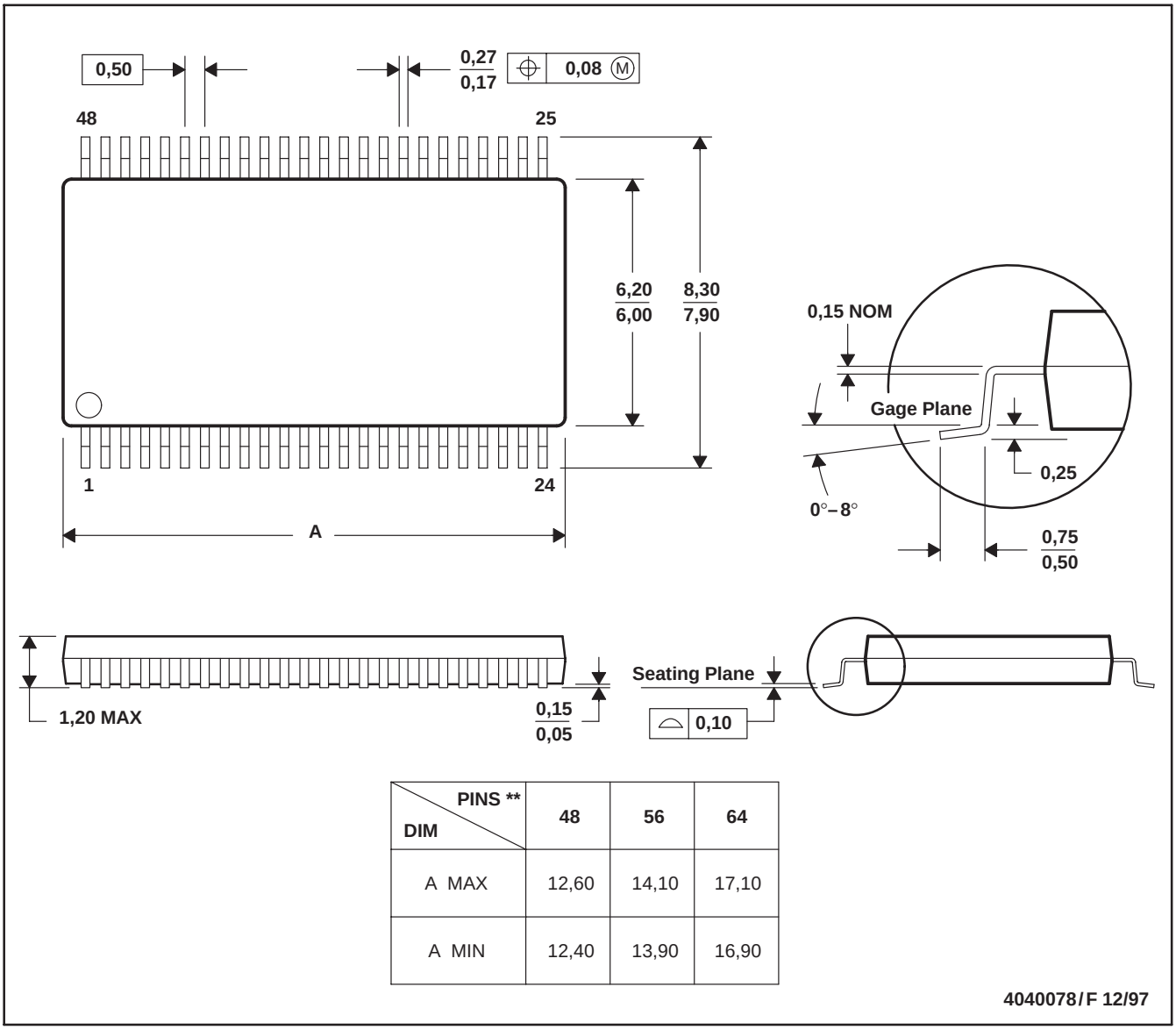



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| SN74ALVCH16820DGGR | TSSOP | DGG | 56 | 2000 | 346.0 | 346.0 | 41.0 |
| SN74ALVCH16820DLR | SSOP | DL | 56 | 1000 | 346.0 | 346.0 | 49.0 |

**DGG (R-PDSO-G**)** **PLASTIC SMALL-OUTLINE PACKAGE**

**48 PINS SHOWN**

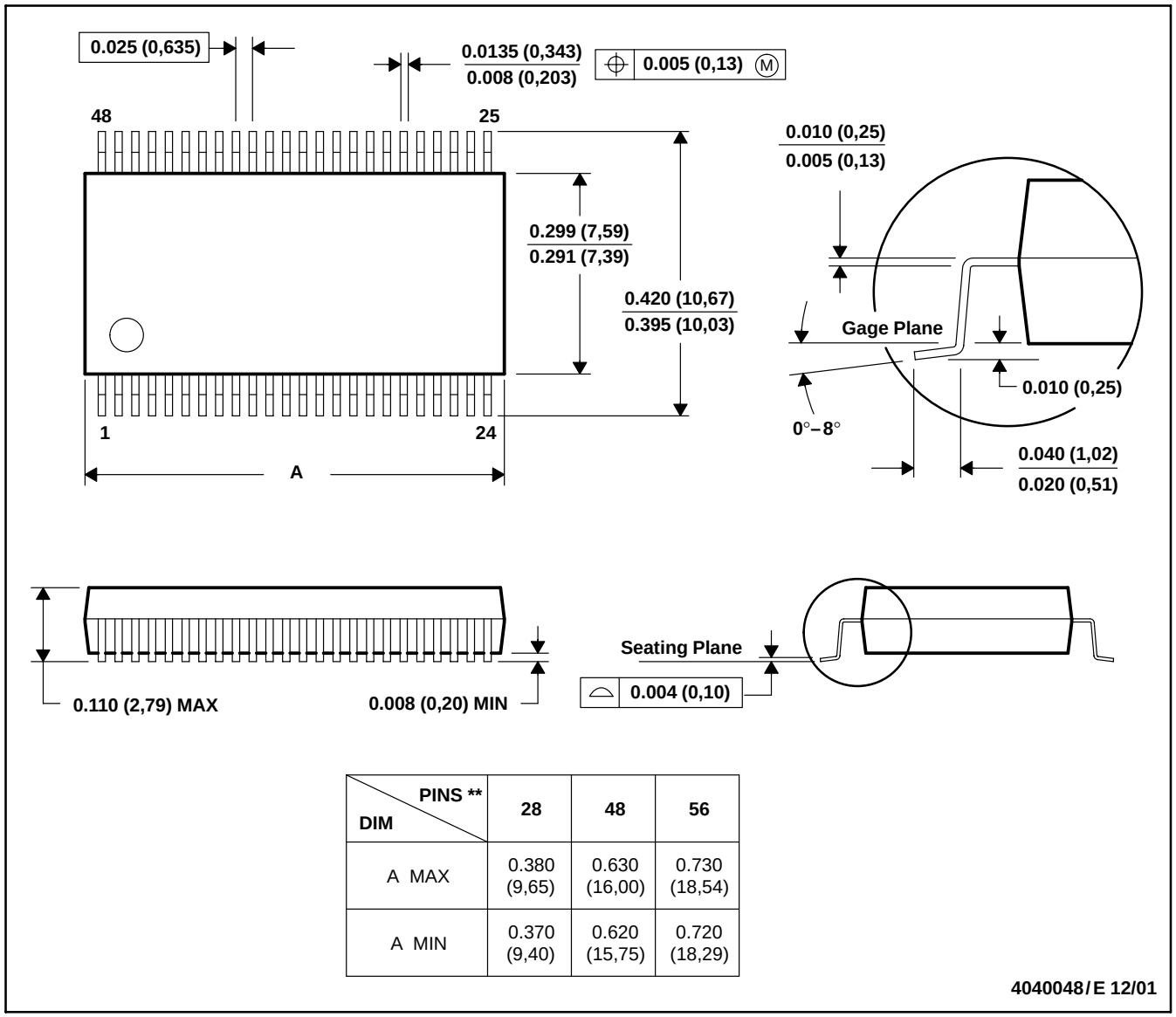



| DIM \ PINS ** | 48 | 56 | 64 |
|---|---|---|---|
| A MAX | 12,60 | 14,10 | 17,10 |
| A MIN | 12,40 | 13,90 | 16,90 |

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

**DL (R-PDSO-G**)** **PLASTIC SMALL-OUTLINE PACKAGE**

**48 PINS SHOWN**




| DIM \ PINS ** | 28 | 48 | 56 |
|---|---|---|---|
| A MAX | 0.380 (9,65) | 0.630 (16,00) | 0.730 (18,54) |
| A MIN | 0.370 (9,40) | 0.620 (15,75) | 0.720 (18,29) |

**4040048/E 12/01**

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MO-118

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